

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Appl. No. 09/974,048

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5. (Amended) A connection structure for connecting a terminal portion of a circuit board with an external terminal formed in an external circuit, wherein said terminal portion is provided with a nickel plating layer and a soldering bump provided on said terminal portion and a thickness of said nickel plating layer is within a range of 1.0 to 2.5 μm .
